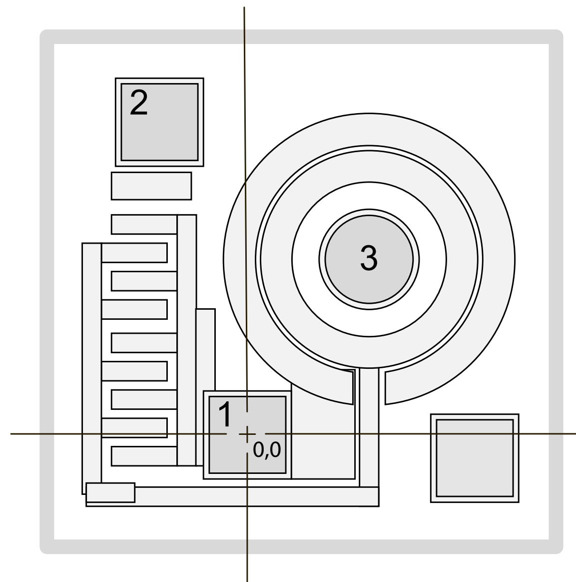
Pad Layout



Backside: Source

Die Specifications

Device	Die Dimensions			Back Side Metal	Back Side	Bonding Pad Material
	Length[1] *(mils)*	Width[1] *(mils)*	Thickness *(mils)*			
LND150	30	30	11 ± 1.5	None	Source Voltage	Al/Cu/Si

Bonding Pad Description

Pad #	Function	x Position[2] *(mils)*	y Position[2] *(mils)*	x Size *(mils)*	y Size *(mils)*
1	Source	0	0	3.9	3.9
2	Gate	-4.7	17.9	3.9	3.9
3	Drain	6.8	10.2	4.3	4.3

Notes:
1. *Maximum values.*
2. *Position referenced to center of pad.*

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